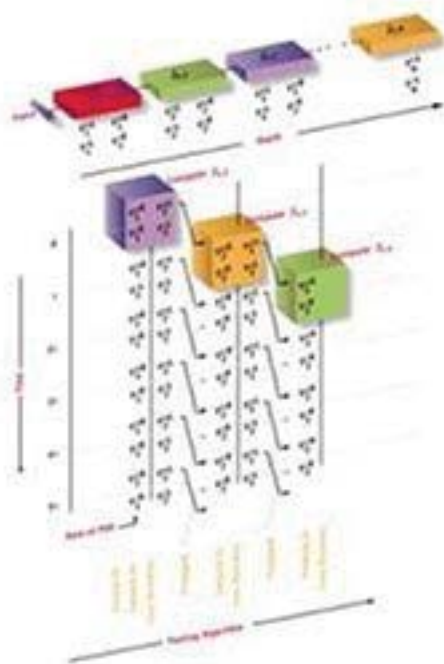


DIGITAL SIGNAL

INTEGRITY



**Modeling
and
Simulation
with
Interconnects
and
Packages**

BRIAN YOUNG

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